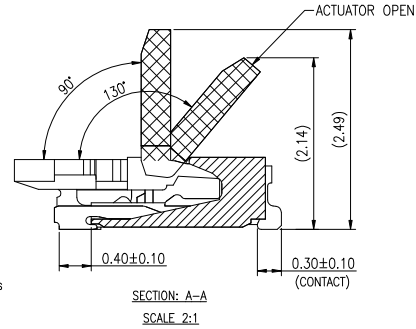
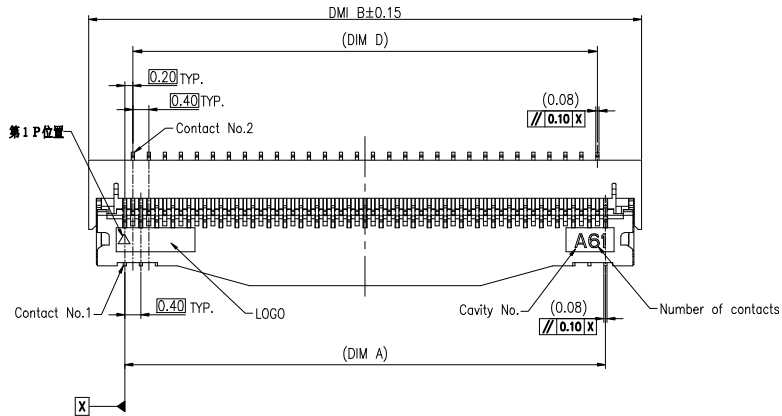
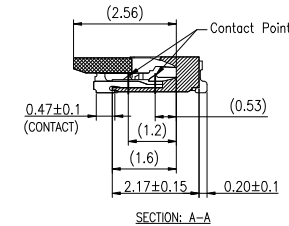
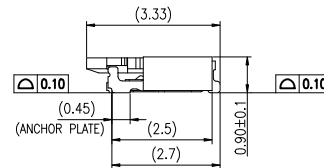
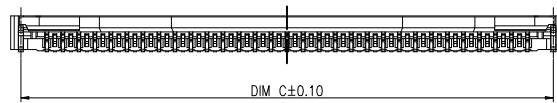
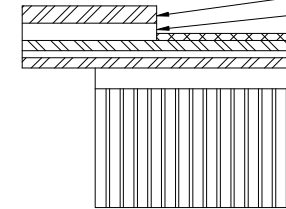
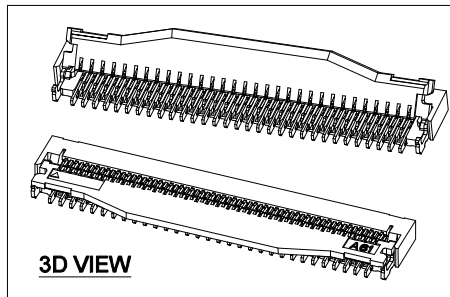




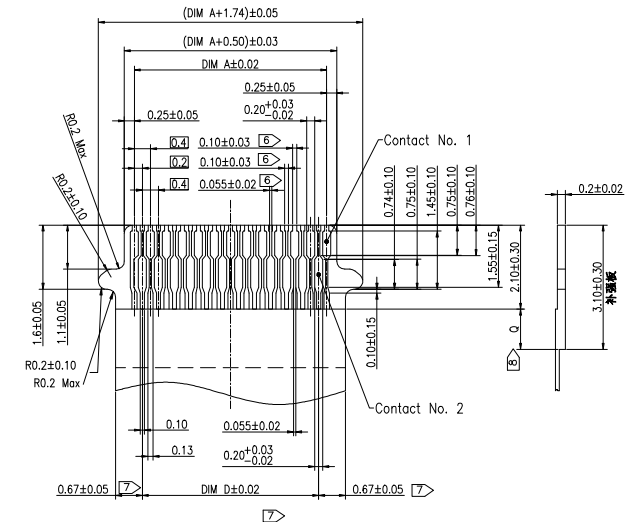
MATERIAL NAME	MATERIAL	THICKNESS(um)
COVERING FILM LAYER	POLYIMIDE 1 mil	25
COVER ADHESIVE		25
SURFACE TREATMENT	1um To 6um NICKEL UNDERPATED 0.2um GOLD PLATED	(4)
COPPER FOIL	Cu 1/3 oz	12
BASE ADHESIVE	HEAT-HARDENED ADHESIVE	No adhesion material
BASE FILM	POLYIMIDE 1 mil	25
REINFORCEMENT MATERIAL ADHESIVE	HEAT-HARDENED ADHESIVE	30
STIFFENER	POLYIMIDE 5 mil	125



No.	Dimensions			
	A	B	C	D
45	8.80	10.60	10.09	8.40
51	10.00	11.80	11.29	9.60
61	12.00	13.80	13.29	11.60
71	14.00	15.80	15.29	13.60

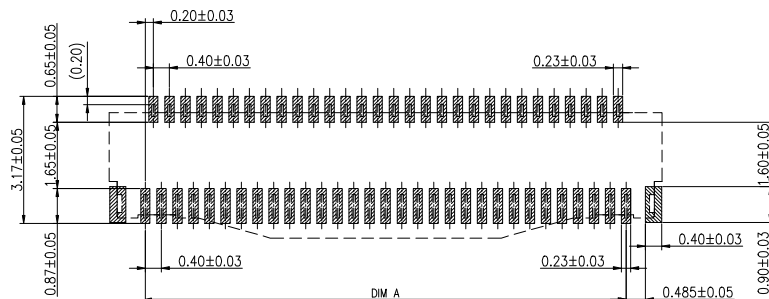


1. MATERIAL:
HOUSING: LCP UL 94V-0 COLOR IS BEIGE
ACTUATOR: PA46 UL94V-0 COLOR IS OR BLACK
CONTACTS: COPPER ALLOY
PEG: COPPER ALLOY
2. PLATING:
 - 2.1 CONTACT AREA:
GOLD FLASH ON CONTACT AREA
50~100u"NICKEL UNDER PLATING OVER ALL.
 - 2.2 SOLDER AREA:
GOLD FLASH ON CONTACT AREA
50~100u"NICKEL UNDER PLATING OVER ALL.
 - 2.3 FITTING:
100~200u" MATT TIN PLATING ON SOLDER
TAILS(LEAD FREE)
50~100u"NICKEL UNDER PLATING OVER ALL.
3. PART NO
OPERATING VOLTAGE: 30Vrms AC
CURRENT RATING: 0.2A DC
OPERATING TEMPERATURE: -55°C~+85°C



RECOMMENDED FPC 1:1

NOTE: ⑥ Shows recommended dimension when lead for plating is required.
⑦ Indicated tolerance is applicable to the exposed conductor.
⑧ Dimenton Q must be 0.5mm minimum.



RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ± 0.05 / THICKNESS $T=0.10\text{mm}$

DESIGN:	Xiping Huang				广东国连电子有限公司 GUANGDONG GUOLIAN ELECTRONICS CO., LTD			
CHECK:	Ke Tian							
APPROVED:	Youquan Xu			TITLE:	0.2翻盖H0.9			
DIM	TOL	DIM	TOL	PART NO.	C0209-61-xxxR1			
X.	±0.25							
X.X	±0.20	X°.	±3.0°	REV. A	SCALE: N/A	UNIT: mm	SHEET: 1/1	
X.XX	±0.15	X.X°						
X.XXX		X.XX°						